Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.024”**



**.016”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .003” X .003”**

**Backside Potential:**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .016” X .024” DATE: 6/22/23**

**MFG: CALOGIC THICKNESS .008” P/N: 2N4351**

**DG 10.1.2**

#### Rev B, 7/19/02